**TOSHIBA** 2SK2842

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOS V)

# 2 S K 2 8 4 2

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 0.4 \Omega$  (Typ.)

High Forward Transfer Admittance :  $|Y_{fS}| = 9.0 \, S$  (Typ.)

Low Leakage Current :  $I_{DSS} = 100 \,\mu\text{A}$  (Max.) ( $V_{DS} = 500 \,\text{V}$ )

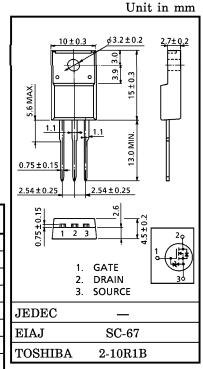
Enhancement-Mode :  $V_{th} = 2.0 \sim 4.0 \text{ V}$ 

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$ 

#### MAXIMUM RATINGS (Ta = 25°C)

CHARACTER	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	500	V	
Drain-Gate Voltage (R	$v_{ m DGR}$	500	V	
Gate-Source Voltage	VGSS	±30	V	
Drain Current	DC	$I_{\mathbf{D}}$	12	Α
Drain Current	Pulse	$I_{ m DP}$	48	Α
Drain Power Dissipation	$P_{\mathbf{D}}$	40	W	
Single Pulse Avalanch	$\mathrm{E}_{\mathrm{AS}}$	364	mJ	
Avalanche Current	$I_{AR}$	12	Α	
Repetitive Avalanche l	$\mathrm{E}_{\mathrm{AR}}$	4.0	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature F	$\mathrm{T_{stg}}$	-55~150	°C	

# INDUSTRIAL APPLICATIONS



Weight: 1.9 g (Typ.)

#### THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

#### Note;

- \* Repetitive rating; Pulse Width Limited by Max. junction temperature.
- \*\*  $V_{DD} = 90 \text{ V}$ , Starting  $T_{ch} = 25^{\circ}\text{C}$ , L = 4.3 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = 12 \text{ A}$

This transistor is an electrostatic sensitive device. Please handle with caution.

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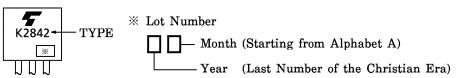
### ELECTRICAL CHARACTERISTICS (Ta = 25°C)

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CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	$I_{GSS}$	$V_{GS} = \pm 25  V,  V_{DS} = 0  V$	_	_	±10	$\mu$ <b>A</b>
Gate-Source 1 Voltage	Breakdown	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS} = 500 \text{ V}, \ V_{GS} = 0 \text{ V}$	_	_	100	$\mu$ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{D} = 10 \text{ mA}, \ V_{GS} = 0 \text{ V}$	500	_	_	V
Gate Thresho	ld Voltage	$V_{ m th}$	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	2.0	_	4.0	V
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}, I_{D} = 6 \text{ A}$	_	0.4	0.52	Ω
Forward Tran Admittance	nsfer	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 6 \text{ A}$	4.0	9.0	_	S
Input Capacitance Reverse Transfer Capacitance		$c_{iss}$	$V_{ m DS} = 10   m V, \ V_{ m GS} = 0   m V, \ f = 1  MHz$	_	2040	_	pF
		$\mathrm{C}_{\mathrm{rss}}$		_	200	_	
Output Capac	citance	Coss		_	640	_	
Switching Time Fall Tim	Rise Time	t <sub>r</sub>	$V_{GS}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$ $V_{OUT}$	_	22	_	
	Turn-on Time	t <sub>on</sub>		_	58	_	ns
	Fall Time	tf		_	36	_	115
	Turn-off Time	t <sub>off</sub>	$V_{\mathrm{IN}}: t_{\mathrm{r}}, t_{\mathrm{f}} < 5  \mathrm{ns}, V_{\mathrm{DD}} \stackrel{=}{=} 200  \mathrm{V}$ $\mathrm{Duty} \stackrel{\leq}{=} 1\%, t_{\mathrm{W}} = 10  \mu \mathrm{s}$		180		
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V},$	_	45	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathrm{D}} = 12\mathrm{A}$	_	25	_	1 110
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{ ext{gd}}$		_	20	_	

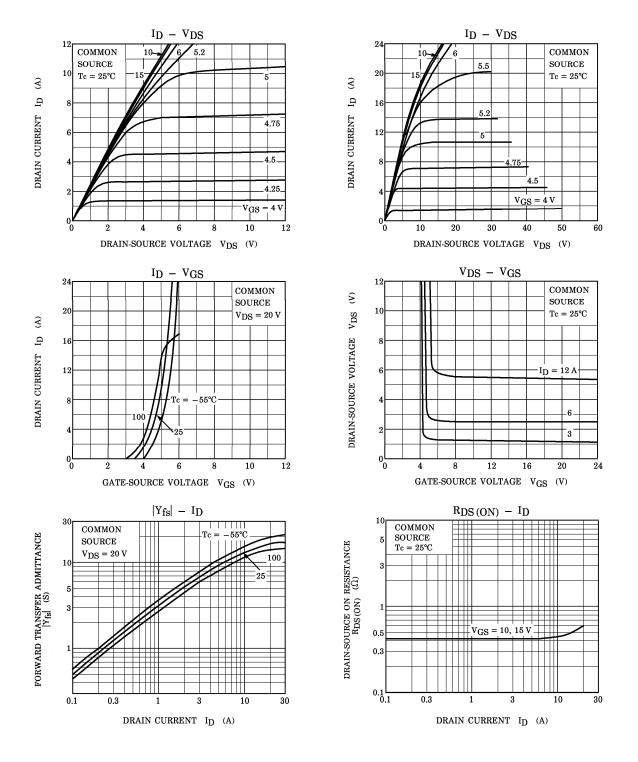
### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

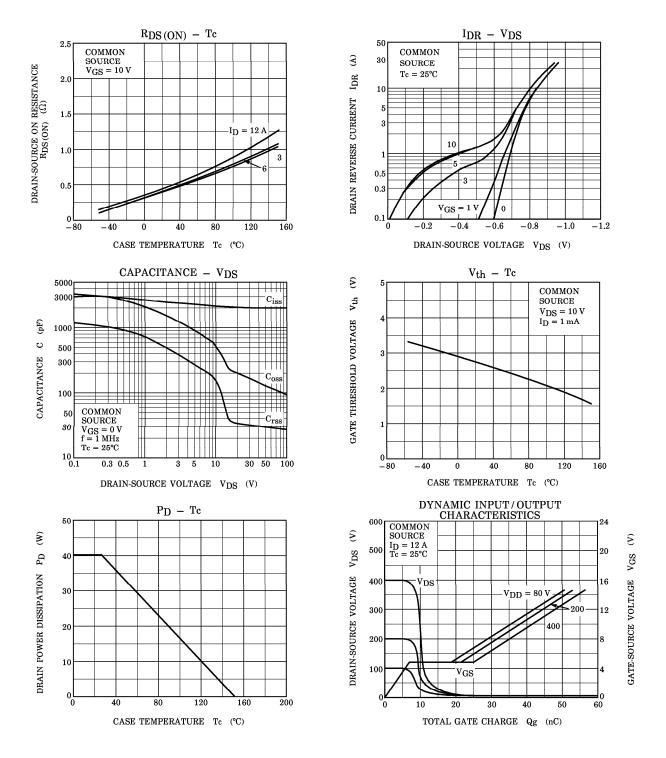
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	12	A
Pulse Drain Reverse Current	${ m I}_{ m DRP}$	_	_	_	48	A
Diode Forward Voltage	$V_{ m DSF}$	$I_{DR} = 12 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse Recovery Time	$t_{rr}$	$I_{DR} = 12 A,  V_{GS} = 0 V$		1200	_	ns
Reverse Recovery Charge	$Q_{rr}$	$\mathrm{dI}_{\mathrm{DR}}$ / $\mathrm{dt}=100\mathrm{A}$ / $\mu\mathrm{s}$	_	16	_	$\mu$ C

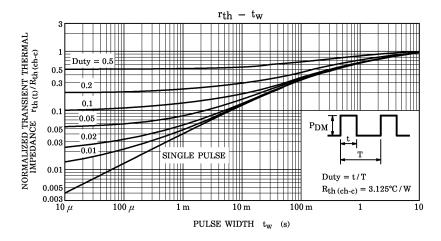
## MARKING

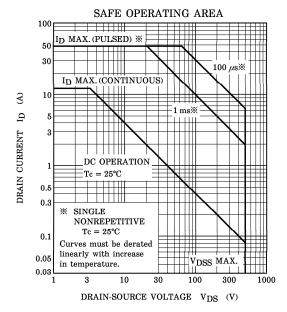


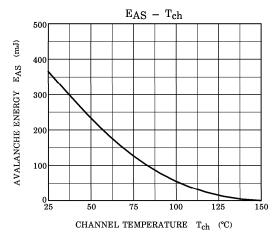
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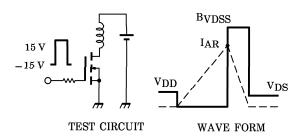












$$\begin{array}{l} Peak~I_{AR}=12~A,~R_G=25~\Omega \\ V_{DD}=90~V,~L=4.3~mH \end{array} ~~E_{AS}=\frac{1}{2}\cdot L\cdot I^2\cdot (\frac{B_{VDSS}}{B_{VDSS}-V_{DD}})$$